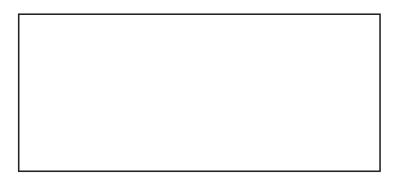


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20583 REV: A	SVN REV: Not In VersionControl		
	TID #: PMP20583			
PLOT NAME = Top Assembly Drawing	GENERATED : 11/28/2016 12:2	26:39 PM TEXAS INSTRUMENTS		



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20583	REV: A	SVN REV	: Not In VersionControl
	TID #: PMP20583			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/28/	2016 12:26:41	PM	TEXAS INSTRUMENTS

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